华润微电子(重庆)有限公司

CRST024N10N4Z

SkyMOS4 N-MOSFET 100V, 2.1mΩ, 180A

Features

- Uses CRM(CQ) advanced SkyMOS4 technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent Q_gx$R_{DS(on)}$ product(FOM)
- Qualified according to JEDEC criteria

Applications

- Motor control and drive
- Battery management
- UPS (Uninterrupible Power Supplies)

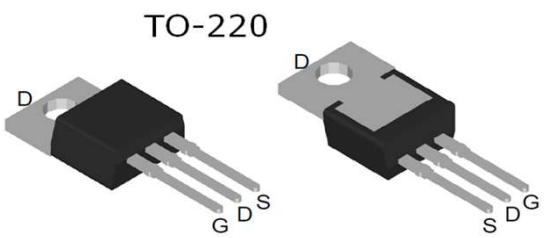
Product Summary

V_{DS}	100V
$R_{DS(on)}$	2.1mΩ
I_D	180A

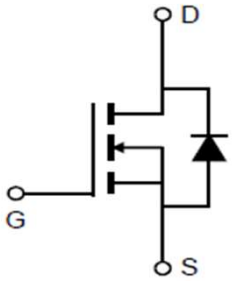
100% DVDS Tested

100% Avalanche Tested

RoHS HF



CRST024N10N4Z



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRST024N10N4Z	CRST024N10N4Z	TO-220	Tube	N/A	N/A	50pcs

Absolute Maximum Ratings

Parameter	**Symbol**	**Value**	**Unit**
Drain-source voltage	V_{DS}	100	V
Continuous drain current T_C = 25°C (Silicon limit) T_C = 25°C (Package limit) T_C = 100°C (Silicon limit)	I_D	 253 180 160	A
Pulsed drain current (T_C = 25°C, t_p limited by T_{jmax})	$I_{D\ pulse}$	720	A
Avalanche energy, single pulse (ID = 45A, Rg=25Ω)	E_{AS}	500	mJ
Gate-Source voltage	V_{GS}	±20	V
Power dissipation (T_C = 25°C)	P_{tot}	250	W
Operating junction and storage temperature	T_j , T_{stg}	-55...+150	°C
Soldering temperature, wave soldering only allowed at leads (1.6mm from case for 10s)	Tsold	260	°C

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Thermal Resistance

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Thermal resistance, junction – case.	R_{thJC}	-	0.30	0.50	°C/W	
Thermal resistance, junction – ambient(min. footprint)	R_{thJA}	-	-	62	°C/W	

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Static Characteristic						
Drain-source breakdown voltage	BV_{DSS}	100	-	-	V	V_{GS}=0V, I_D=250uA
Gate threshold voltage	$V_{GS(th)}$	2.2	3	3.8	V	V_{DS}=V_{GS},I_D=250uA
Zero gate voltage drain current	I_{DSS}	- -	- -	1 100	μA	V_{DS}=100V,V_{GS}=0V T_j=25°C T_j=125°C
Gate-source leakage current	I_{GSS}	-	±10	±100	nA	V_{GS}=±20V,V_{DS}=0V
Drain-source on-state resistance	$R_{DS(on)}$	-	2.1	2.5	mΩ	V_{GS}=10V, I_D=90A TO-220
Transconductance	g_{fs}	-	197.2	-	S	V_{DS}=5V,I_D=90A
Dynamic Characteristic						
Input Capacitance	C_{iss}	7565	11347	17020.5	pF	V_{GS}=0V, V_{DS}=50V, f=1MHz
Output Capacitance	C_{oss}	1167	1751	4376		
Reverse Transfer Capacitance	C_{rss}	25	37	259		
Gate Total Charge	Q_G	103	154	232	nC	V_{GS}=10V, V_{DS}=50V, I_D=90A, f=1MHz
Gate-Source charge	Q_{gs}	44	66	98		
Gate-Drain charge	Q_{gd}	12	18	35		

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Turn-on delay time	$t_{d(on)}$	19	29	43	ns	V_{GS}=10V, V_{DD}=50V, R_{G_ext}=3.0Ω
Rise time	t_r	76	114	170		
Turn-off delay time	$t_{d(off)}$	52	78	117		
Fall time	t_f	72	109	163		
Gate resistance	R_G	1	1.6	2.5	Ω	V_{GS}=0V, V_{DS}=0V, f=1MHz

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	0.9	1.4	V	V_{GS}=0V,I_{SD}=90A
Body Diode Continuous Forward Current	I_S	-	-	180	A	T_C = 25°C
Body Diode Pulsed Current	$I_{S\ pulse}$	-	-	720	A	T_C = 25°C
Body Diode Reverse Recovery Time	t_{rr}	49	99	197	ns	I_F=90A, dI/dt=100A/μs
Body Diode Reverse Recovery Charge	Q_{rr}	109	218	436	nC	

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Typical Performance Characteristics

Fig 1: Output Characteristics

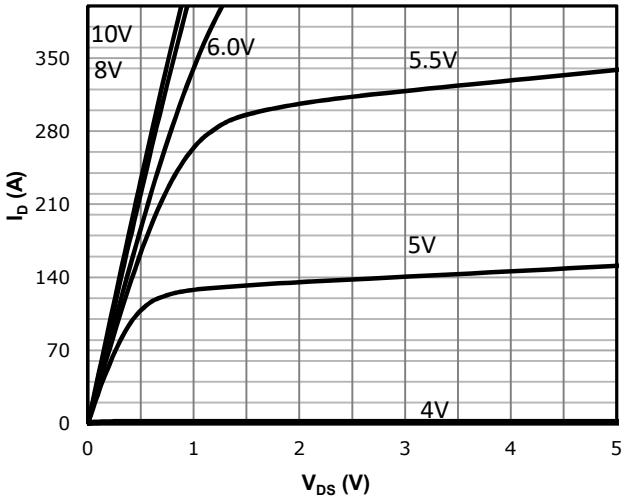
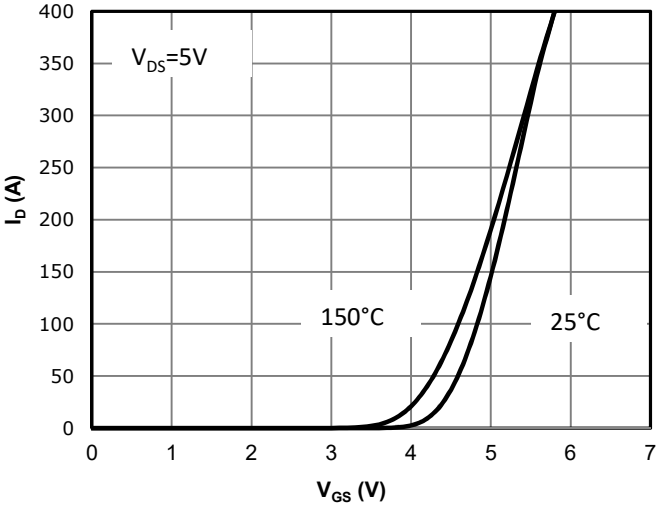


Fig 2: Transfer Characteristics



3: Rds(on) vs Drain Current and Gate Voltage

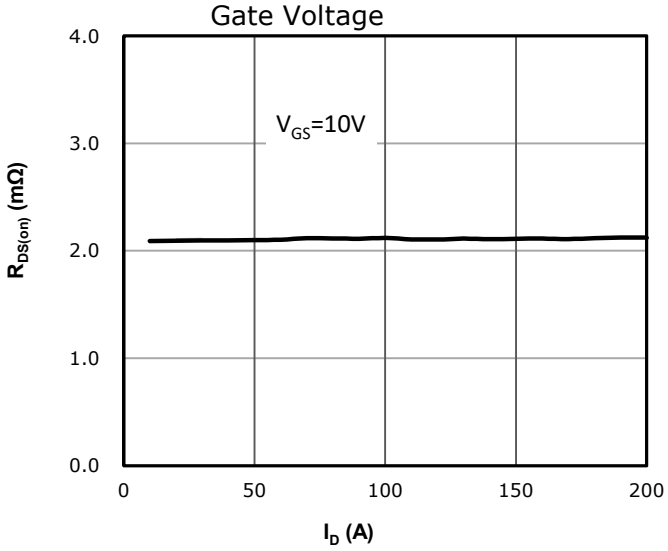


Fig 4: Rds(on) vs Gate Voltage

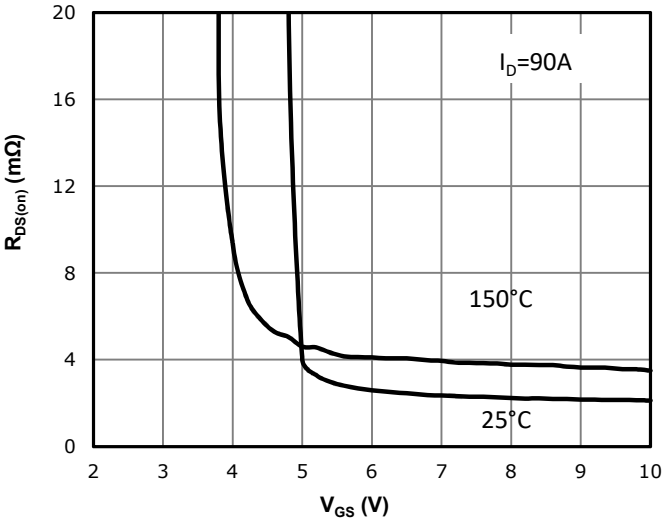


Fig 5: Rds(on) vs. Temperature

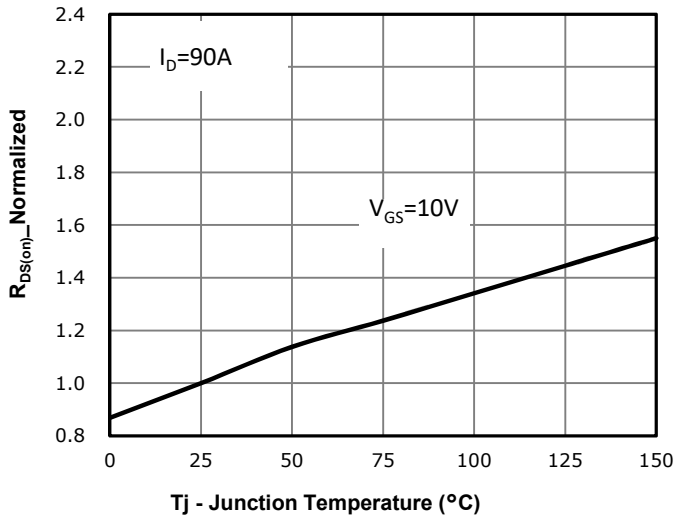
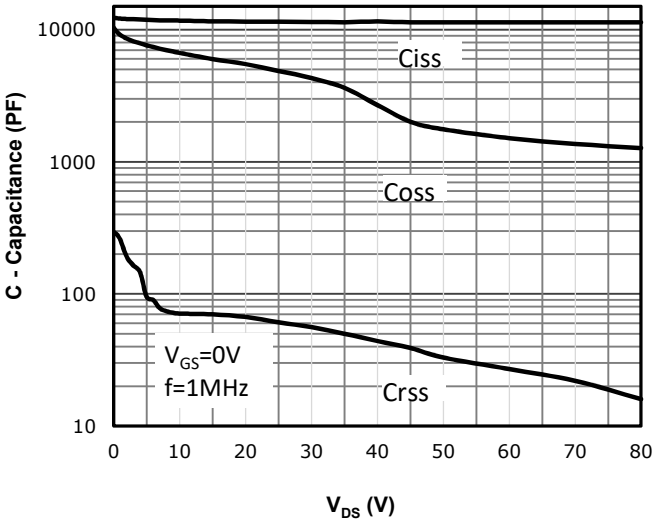


Fig 6: Capacitance Characteristics



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Fig 7: Gate Charge Characteristics

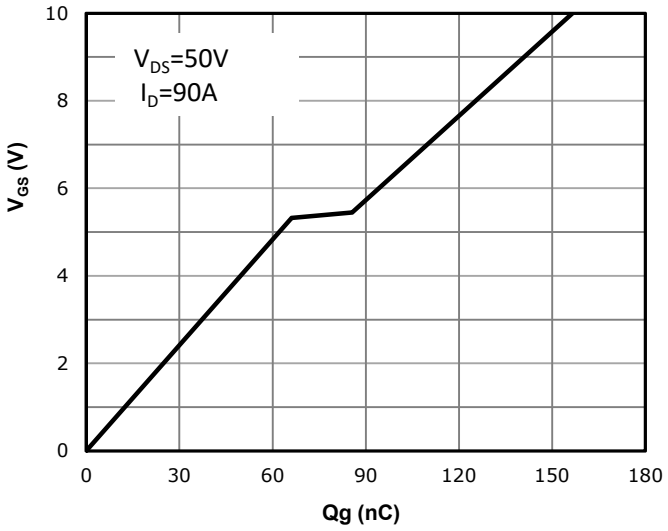


Fig 8: Body-diode Forward Characteristics

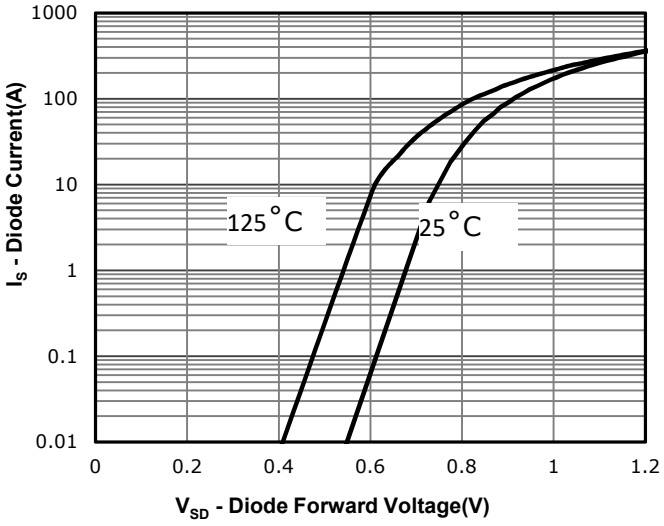


Fig 9: Power Dissipation

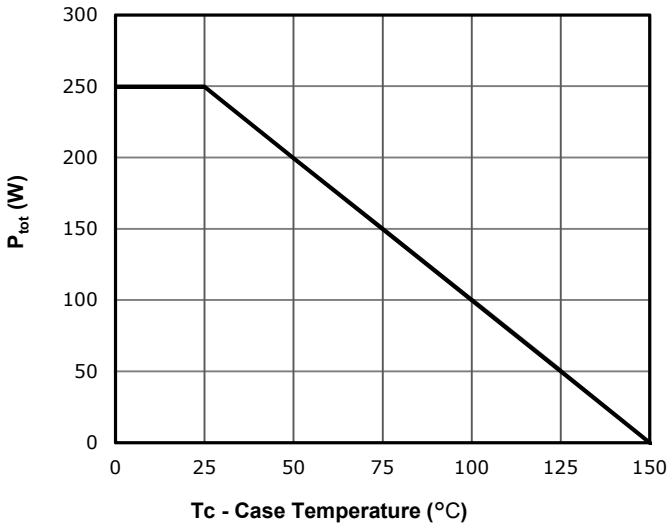


Fig 10: Drain Current Derating

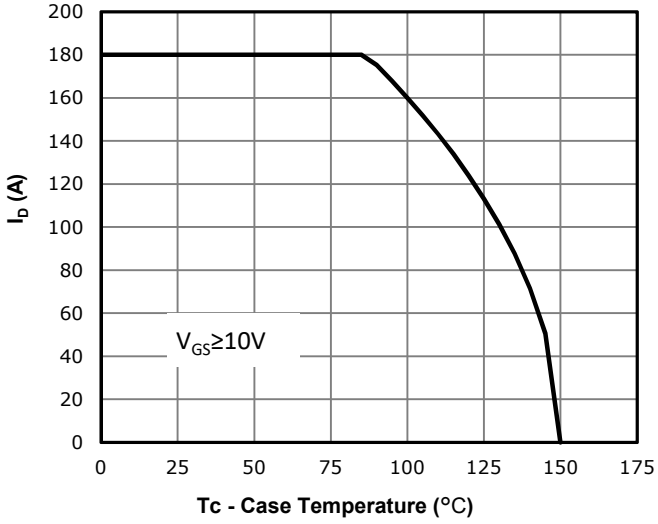


Fig 11: BVds vs. Temperature

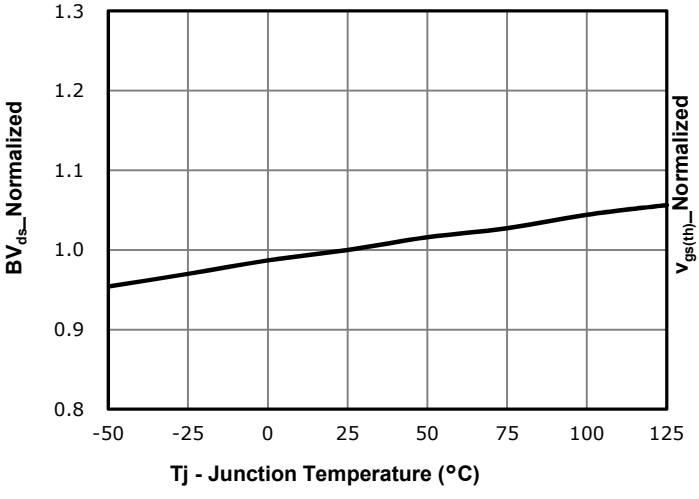
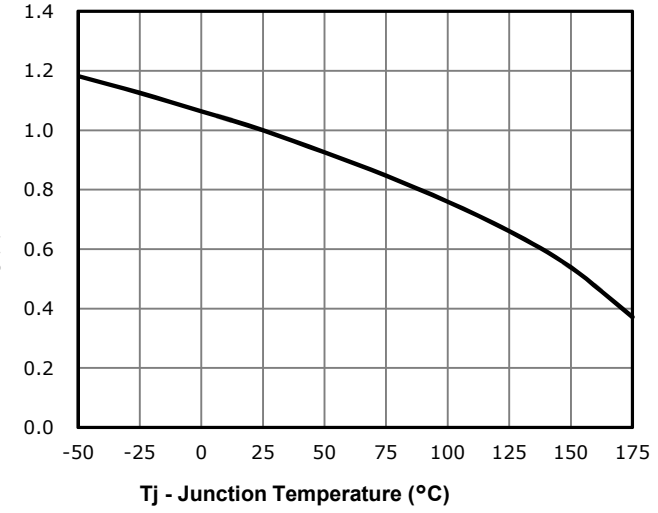


Fig 6: Vgs(th) vs. Temperature



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Fig 13: Safe Operating Area

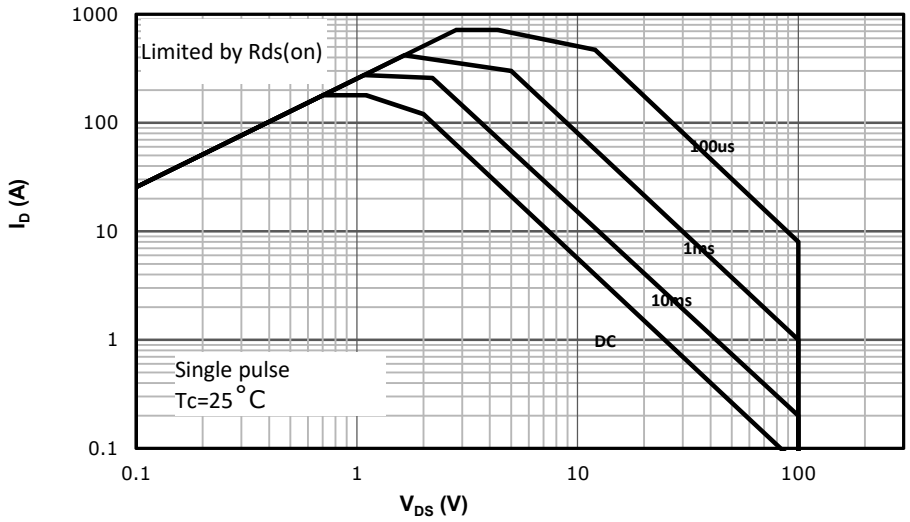
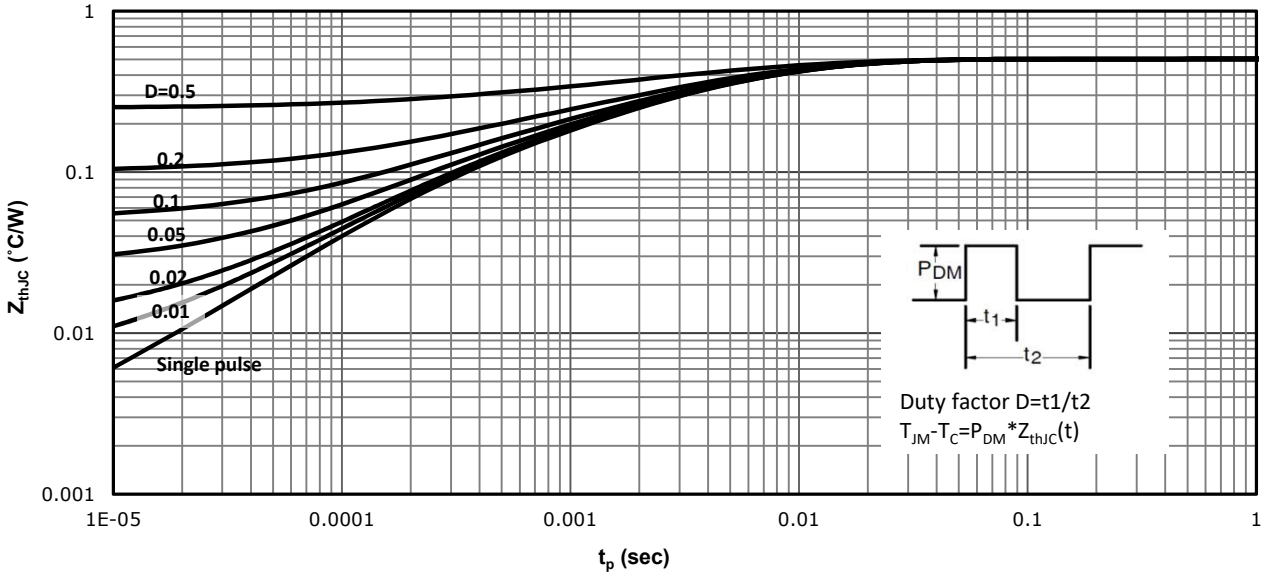


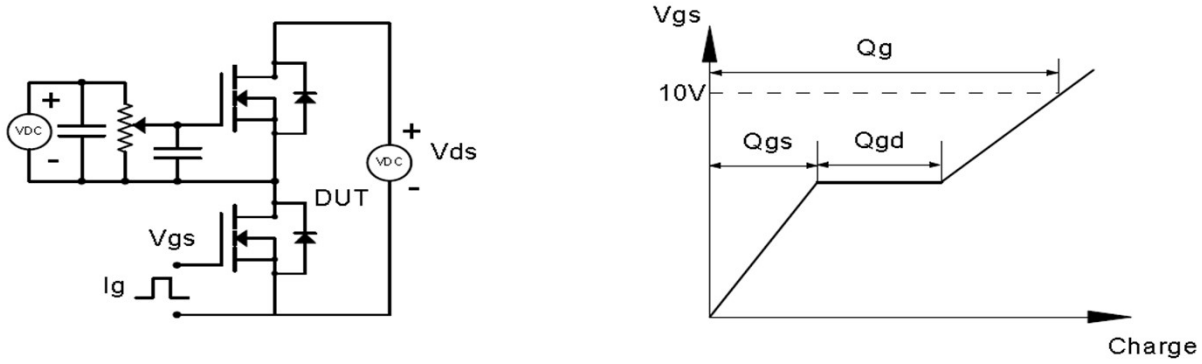
Fig 14: Max. Transient Thermal Impedance



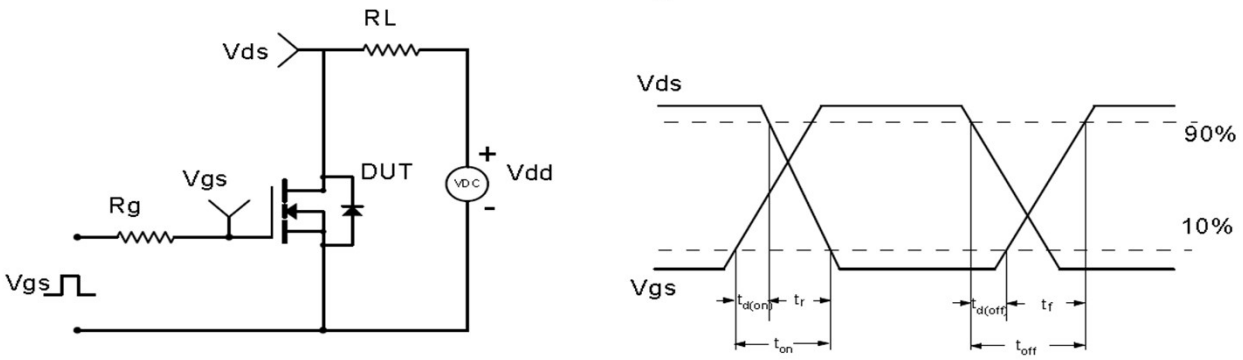
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Test Circuit & Waveform

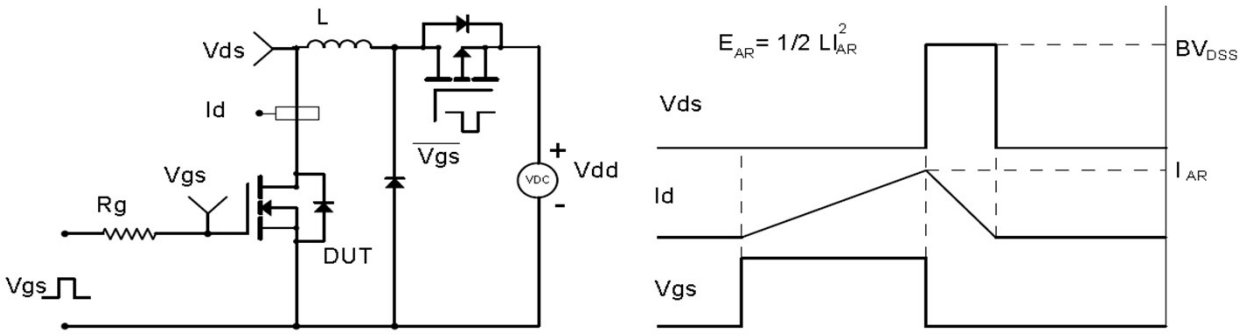
Gate Charge Test Circuit & Waveform



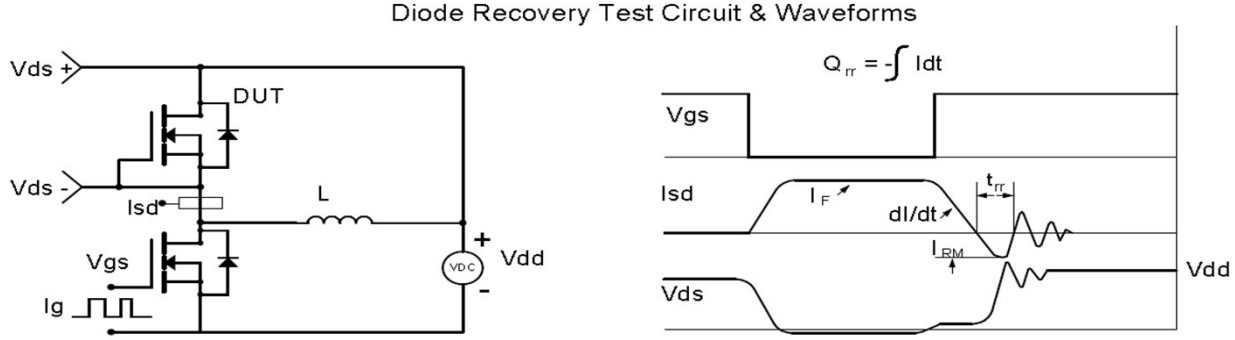
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

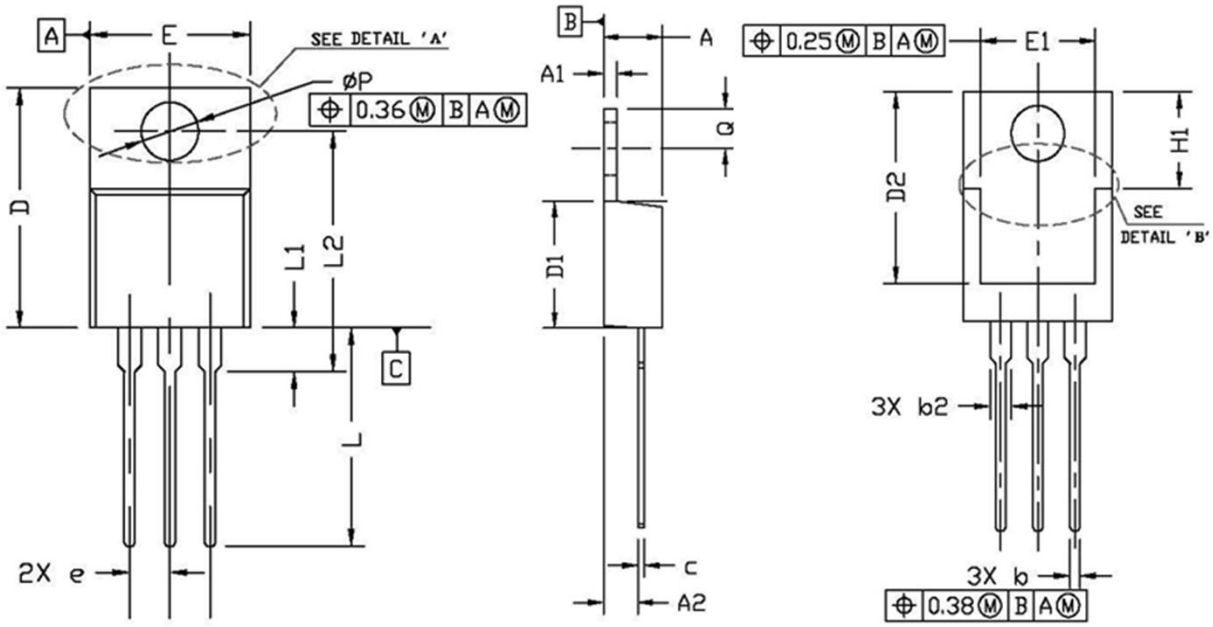


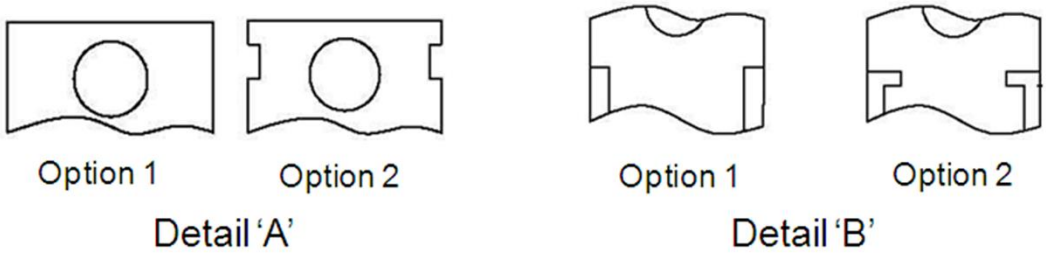
Diode Recovery Test Circuit & Waveforms



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Package Outline: TO-220-3L



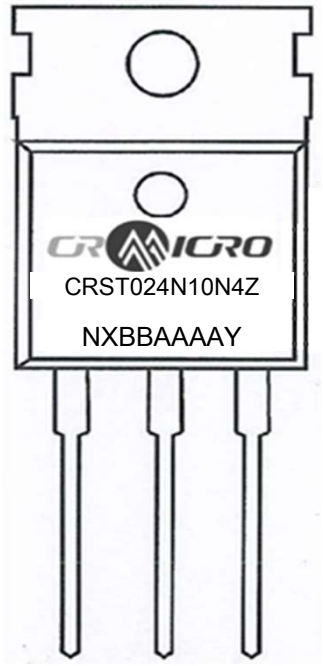


Detail 'A' Detail 'B'

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.42	4.72	0.174	0.186
A1	1.20	1.40	0.047	0.055
A2	2.35	2.90	0.093	0.114
b	0.71	0.91	0.028	0.036
b2	1.20	1.38	0.047	0.054
c	0.45	0.60	0.018	0.024
D	14.70	16.00	0.579	0.630
D1	8.80	9.50	`	0.374
D2	11.75	13.60	0.463	0.535
e	2.54 BSC.		0.100 BSC.	
E	9.70	10.40	0.382	0.409
E1	7.00	8.90	0.276	0.350
H1	6.10	6.50	0.240	0.256
L	12.80	14.80	0.504	0.583
L1	2.50	3.90	0.098	0.154
L2	12.13	16.50	0.478	0.650
Q	2.60	3.00	0.102	0.118
P	3.55	3.90	0.140	0.154

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Marking



NOTE:
NXBBAAAAY

N	—Wire Bond code
X	—Assembly location code
BB	—Fab code
AAAA	—Lot code
Y	—Bin code

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Revision History

Revison	Date	Major changes
1.0	2022/8/31	Release of Preliminary version

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qulified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semicondutor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.

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